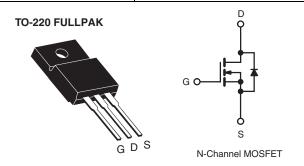


Vishay Siliconix

Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	250			
$R_{DS(on)}\left(\Omega\right)$	V _{GS} = 10 V	0.45		
Q _g (Max.) (nC)	41			
Q _{gs} (nC)	6.5			
Q _{gd} (nC)	22			
Configuration	Single			



FEATURES

- · Isolated Package
- High Voltage Isolation = 2.5 kV_{RMS} (t = 60 s; f = 60 Hz)



COMPLIANT

- Sink to Lead Creepage Distance = 4.8 mm
- · Dynamic dV/dt Rating
- Low Thermal Resistance
- · Lead (Pb)-free Available

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The moulding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION			
Package	TO-220 FULLPAK		
Lead (Pb)-free	IRFI634GPbF		
	SiHFI634G-E3		
SnPb	IRFI634G		
	SiHFI634G		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	250	V	
Gate-Source Voltage			V_{GS}	± 20	V	
Continuous Drain Current	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	1-	5.6	А	
		T _C = 100 °C	ID	3.5		
Pulsed Drain Current ^a			I _{DM}	22		
Linear Derating Factor				0.28	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	300	mJ	
Repetitive Avalanche Currenta			I _{AR}	5.6	Α	
Repetitive Avalanche Energy ^a			E _{AR}	3.5	mJ	
Maximum Power Dissipation	T _C = 25 °C		P_{D}	35	W	
Peak Diode Recovery dV/dt ^c			dV/dt	4.8	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		· ·	300 ^d	7	
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 15 mH, R_G = 25 Ω , I_{AS} = 5.6 A (see fig. 12).
- c. $I_{SD} \leq 5.6$ A, $dI/dt \leq 120$ A/µs, $V_{DD} \leq V_{DS}, \, T_J \leq 150$ $^{\circ}C.$
- d. 1.6 mm from case.
- * Pb containing terminations are not RoHS compliant, exemptions may apply

IRFI634G, SiHFI634G

Vishay Siliconix



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	3.6	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static							•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	250	-	-	V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	-	0.30	-	V/°C		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2.0	-	4.0	V	
Gate-Source Leakage	I _{GSS}	,	V _{GS} = ± 20 V		-	± 100	nA	
Zava Cata Valtana Dunin Occurrent		V _{DS} =	V _{DS} = 250 V, V _{GS} = 0 V		-	25	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200 V	V _{DS} = 200 V, V _{GS} = 0 V, T _J = 125 °C		-	250		
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.4 A ^b	-	-	0.45	Ω	
Forward Transconductance	9 _{fs}	V _{DS} =	= 50 V, I _D = 3.4 A ^b	2.5	-	-	S	
Dynamic				•	•	•	,	
Input Capacitance	C _{iss}	$V_{GS} = 0 V$,		-	770	-	pF	
Output Capacitance	C _{oss}		$V_{DS} = 25 V$,		190	-		
Reverse Transfer Capacitance	C _{rss}	f = 1.0 MHz, see fig. 5 f = 1.0 MHz		-	52	-		
Drain to Sink Capacitance	С			-	12	-		
Total Gate Charge	Qg		I _D = 5.6 A, V _{DS} = 200 V, see fig. 6 and 13 ^b	-	-	41	nC	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V		-	-	6.5		
Gate-Drain Charge	Q _{gd}	See lig. 0 and 10		-	-	22	1	
Turn-On Delay Time	t _{d(on)}	V_{DD} = 125 V, I_{D} = 5.6 A, R_{G} = 12 Ω , R_{D} = 22 Ω , see fig. 10 ^b		-	9.6	-	ns	
Rise Time	t _r			-	21	-		
Turn-Off Delay Time	t _{d(off)}			-	42	-		
Fall Time	t _f			-	19	-		
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-		
Internal Source Inductance	L _S			-	7.5	-	nH	
Drain-Source Body Diode Characteristic	s			•			·	
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	5.6	А	
Pulsed Diode Forward Current ^a	I _{SM}			-	-	22	A	
Body Diode Voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, \ I_S = 5.6 \text{A}, \ V_{GS} = 0 \text{V}^{\text{b}}$				2.0	V	
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 5.6 A, dl/dt = 100 A/μs ^b		_	220	440	ns	
Body Diode Reverse Recovery Charge	Q _{rr}				1.2	2.4	μC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-or			n-on is dominated by L _S and L _D)			

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 $\mu s;$ duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

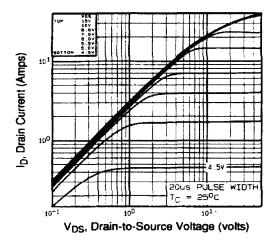


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

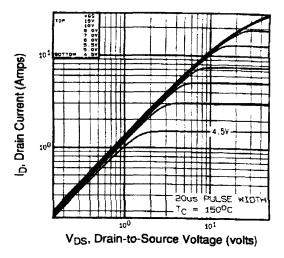


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

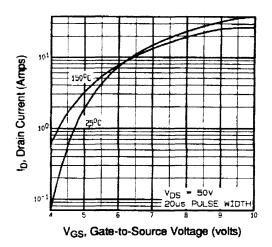


Fig. 3 - Typical Transfer Characteristics

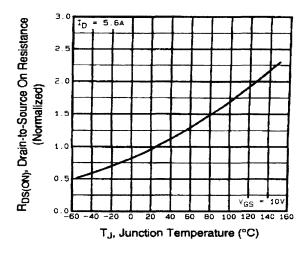


Fig. 4 - Normalized On-Resistance vs. Temperature

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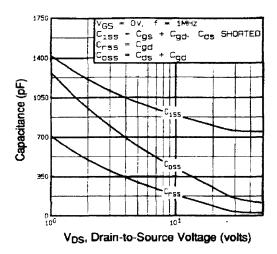


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

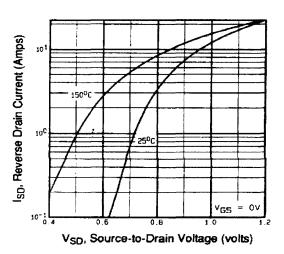


Fig. 7 - Typical Source-Drain Diode Forward Voltage

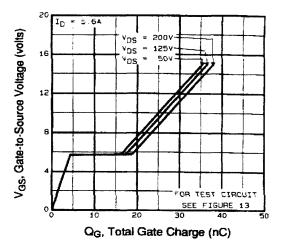


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

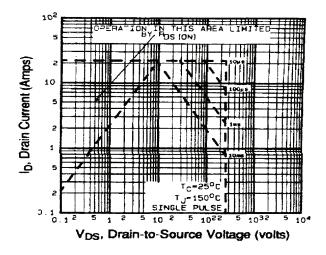


Fig. 8 - Maximum Safe Operating Area



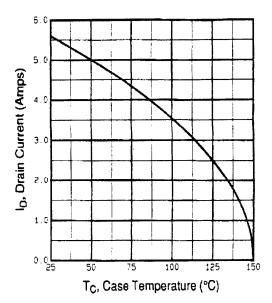


Fig. 9 - Maximum Drain Current vs. Case Temperature

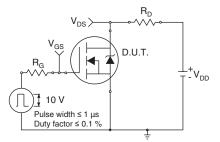


Fig. 10a - Switching Time Test Circuit

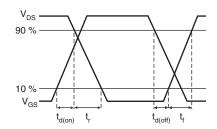


Fig. 10b - Switching Time Waveforms

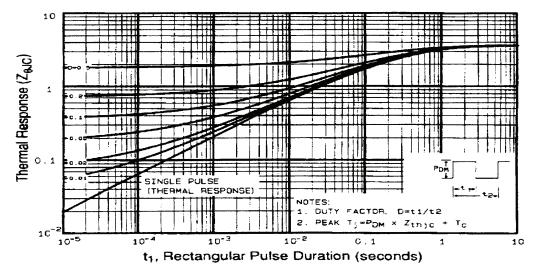


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

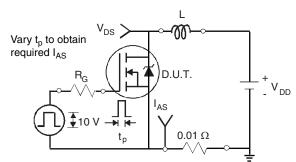


Fig. 12a - Unclamped Inductive Test Circuit

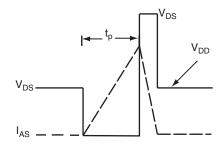


Fig. 12b - Unclamped Inductive Waveforms

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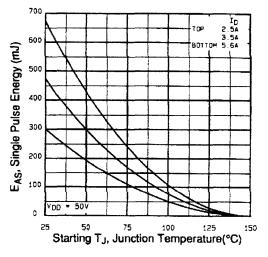


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

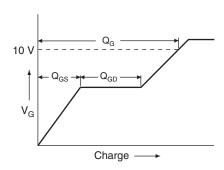


Fig. 13a - Basic Gate Charge Waveform

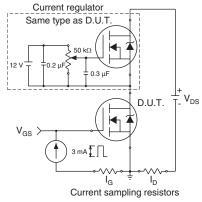
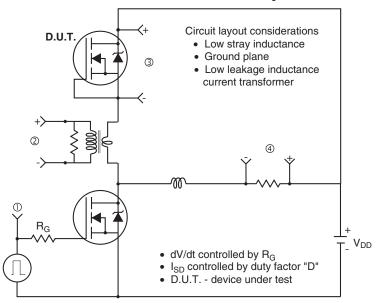
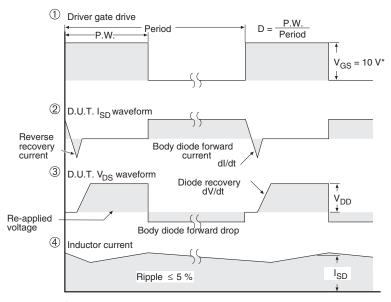


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit





* V_{GS} = 5 V for logic level devices and 3 V drive devices

Fig. 14 - For N-Channel

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